



High Performance Grating-Outcoupled Surface Emitting(GSE) Lasers Using Quantum Well Intermixing

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Outline

- **1st ion implantation result summary**
- **2nd simulations of interdiffusion**
 - **Brief introduction of Diffusion**
 - **Simulation results**
- **Future Work**



1st ion implantation result summary

- Ion implantation: 100keV energy, dose $5e14$ cm⁻², substrate temp 200C
- Disorder observed in BDR regions:
 - Maximum wavelength shift: 17.1 nm, RTA @ 675C, 12 mins
 - Wavelength shift of 15 nm occurred, RTA @ 800C, 3 mins
- Dielectric encapsulation Challenges:
 - During RTA, SiNx of 400 Å couldn't hold at high temperature for long time: RTA @ 675C greater than 2 mins



2nd ion implantation

- Same ion implantation conditions
- AlGaInAs (1550nm and 1310nm) wafers and InGaAsP wafers



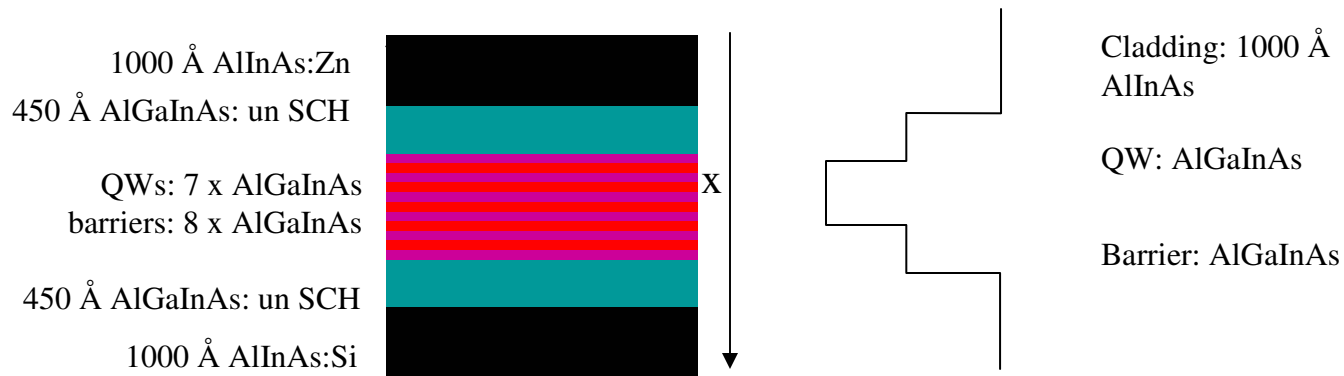
Brief introduction of Diffusion

- Fick's first law of diffusion $J = -D\partial N(x,t) / \partial x$ (1)
- Continuity equation for particle flux $\partial N / \partial t = -\partial J / \partial x$ (2)
- Fick's second law of diffusion $\partial N / \partial t = D\partial^2 N / \partial x^2$ (3)
- Solutions of interest are in the form:
$$N(x,t) = N_0 \operatorname{erfc}(x / 2\sqrt{Dt})$$
 (4)

J is the particle flux, N is the concentration of the particle, D is the diffusion coefficient, N_0 is the particle concentration at the interface ($x=0$).



Solutions after matching boundary conditions of the quantum well structure: Single QW Simulation



$$D = D_0 \exp(-E_A / kT) \quad (5)$$

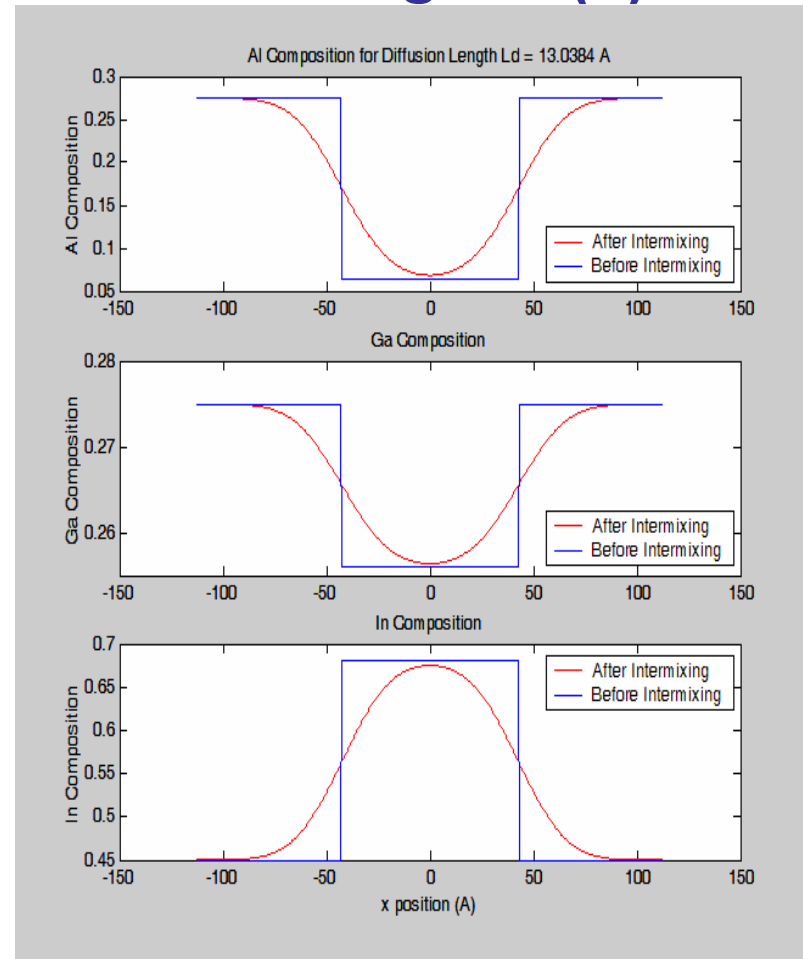
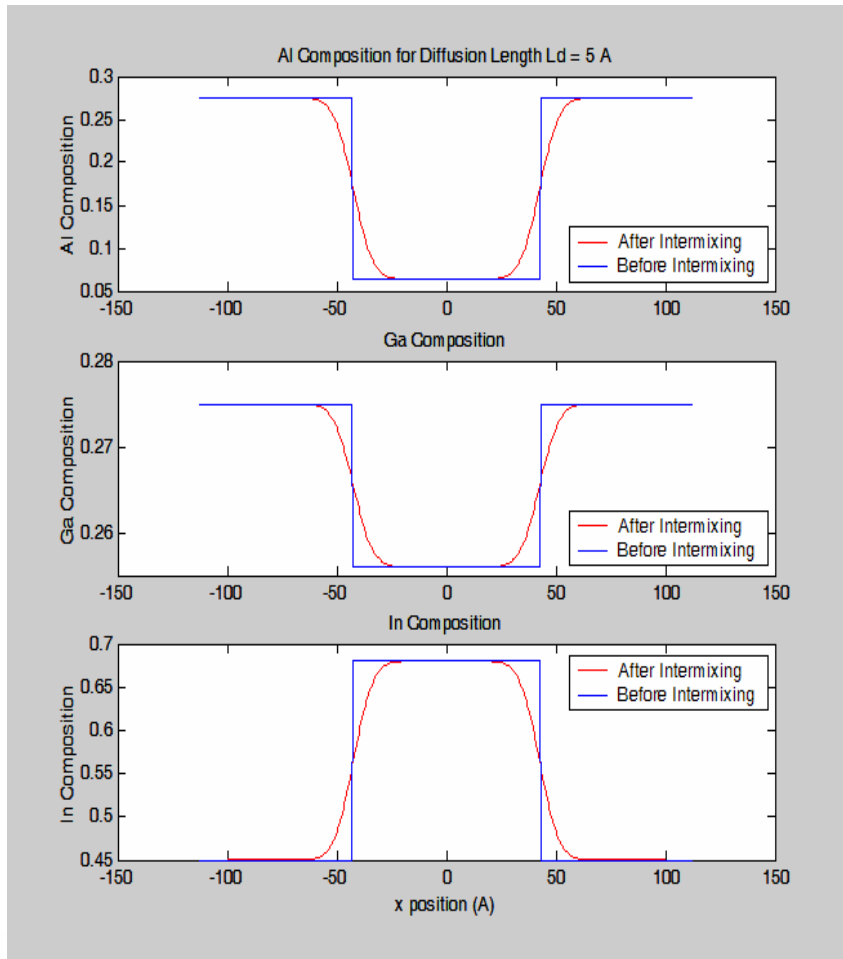
$$L_d = \sqrt{D \cdot t} \quad (6)$$

$$y(x) = y_0 + \frac{\Delta y_0}{2} \left[\operatorname{erf} \left(\frac{(L_x + 2x)}{4L_d} \right) + \operatorname{erf} \left(\frac{(L_x - 2x)}{4L_d} \right) \right] \quad (7)$$

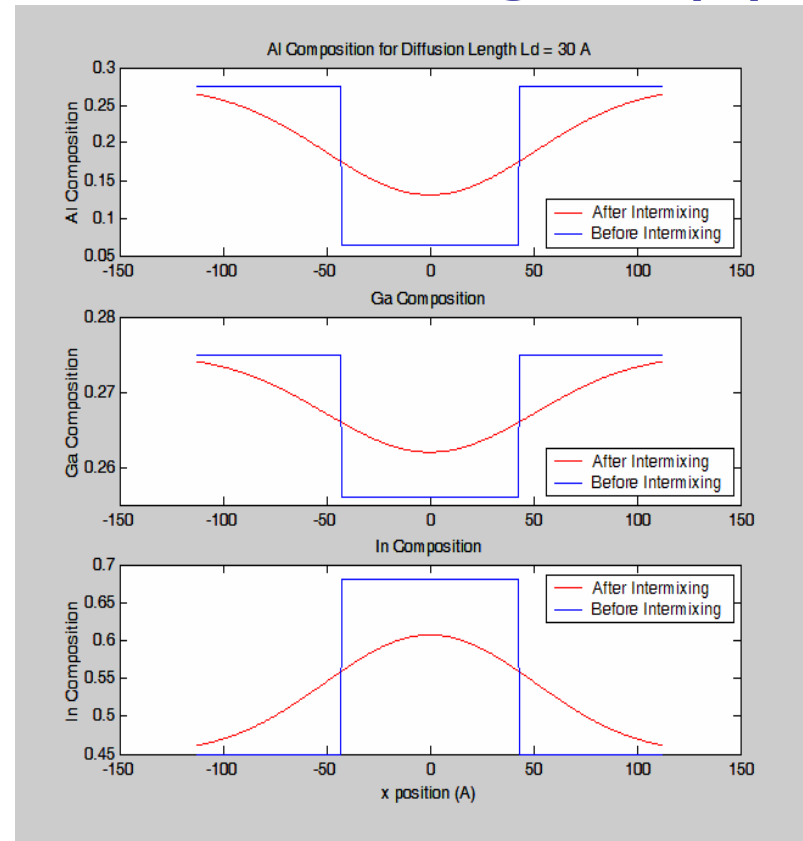
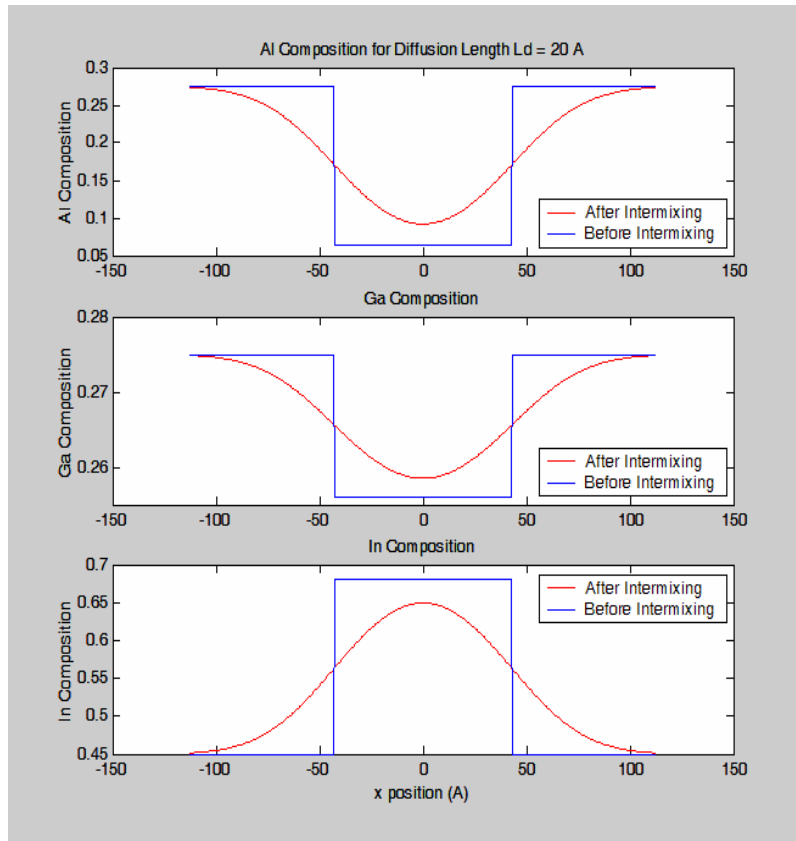
D is the diffusion coefficient, E_A is activation energy, k is Boltzmann's constant, T is temperature, $y(x)$ is the compositional profile, y_0 is the initial composition profile, Δy_0 is the composition difference between quantum well and barrier. L_x is the quantum well width, L_d is the diffusion length, x is the growth direction



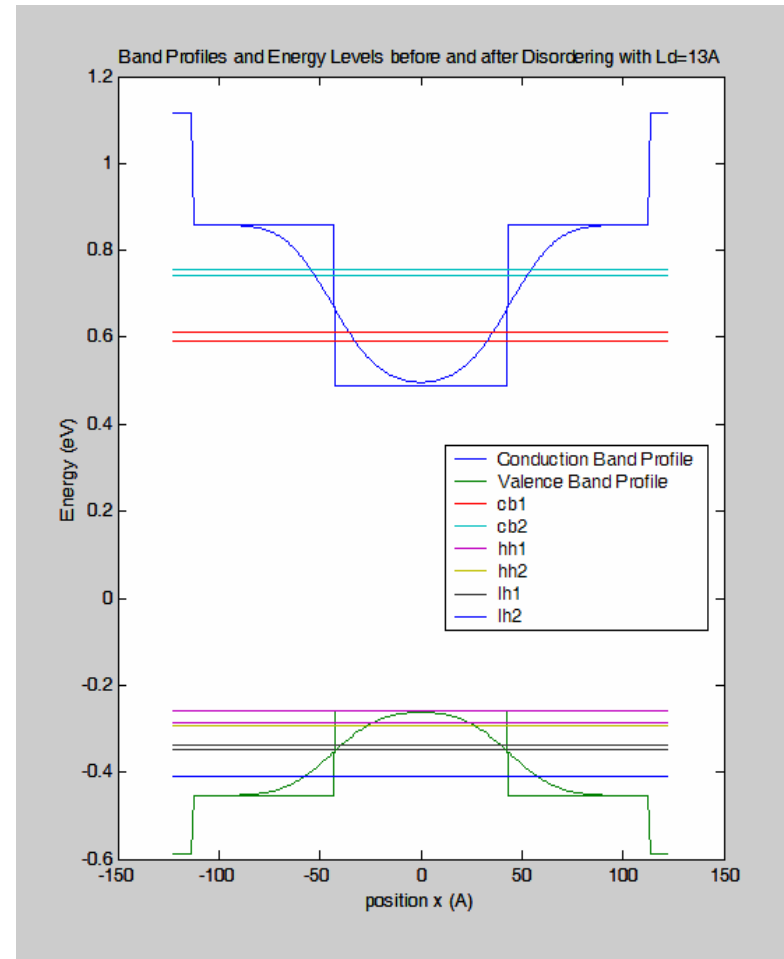
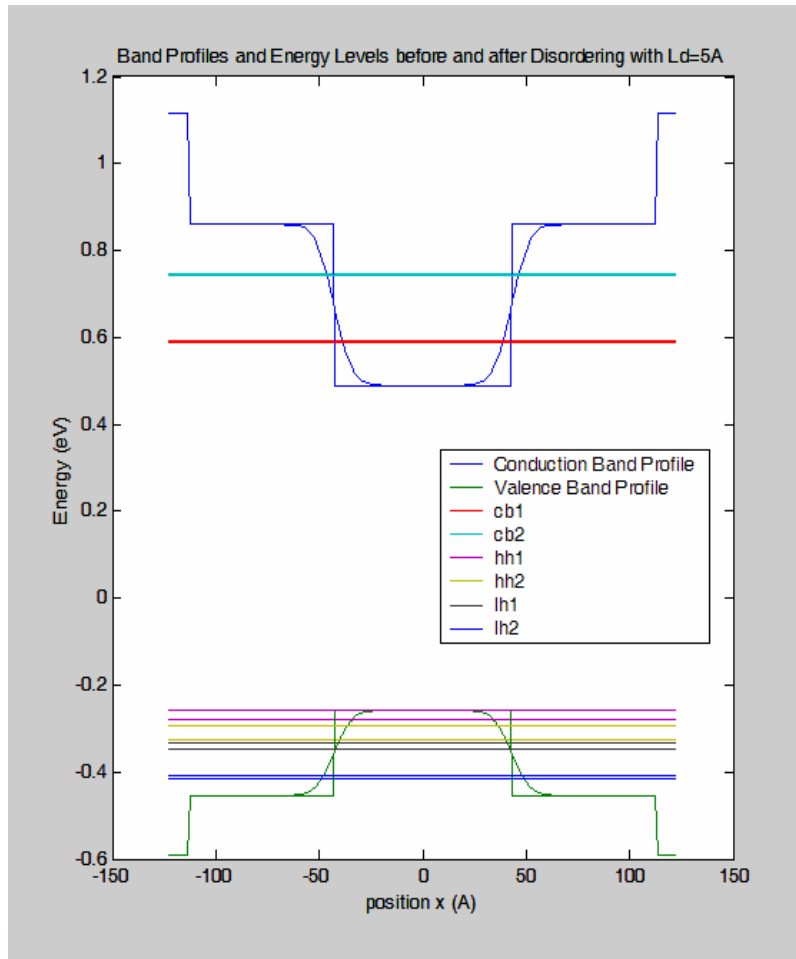
Simulations for different diffusion lengths (1)



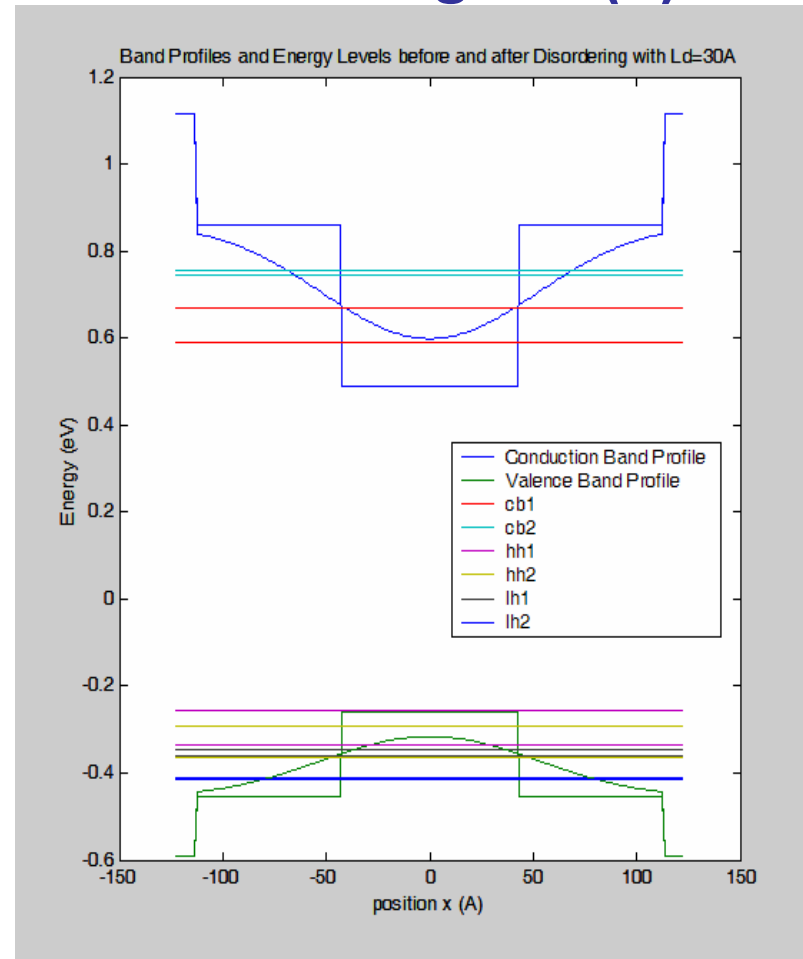
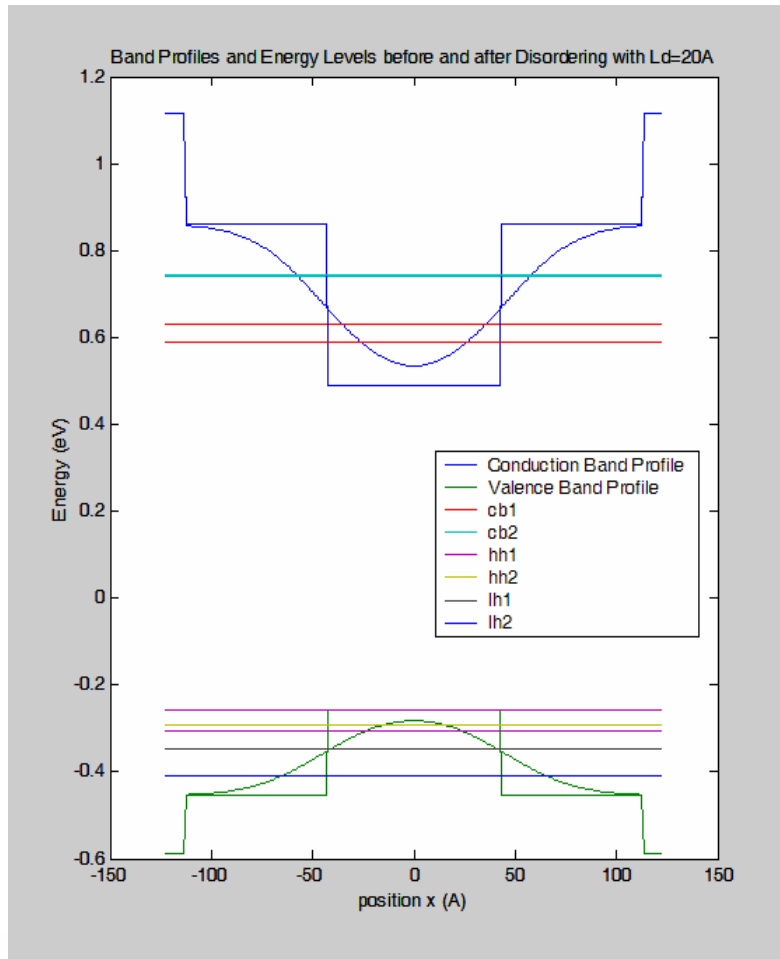
Simulations for different diffusion lengths (2)



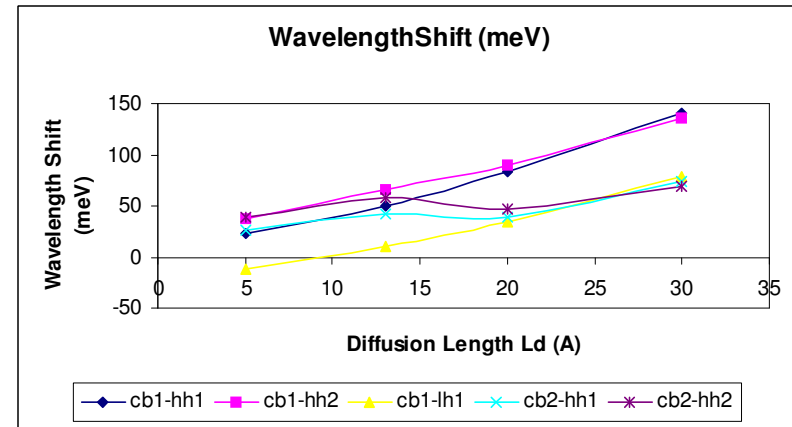
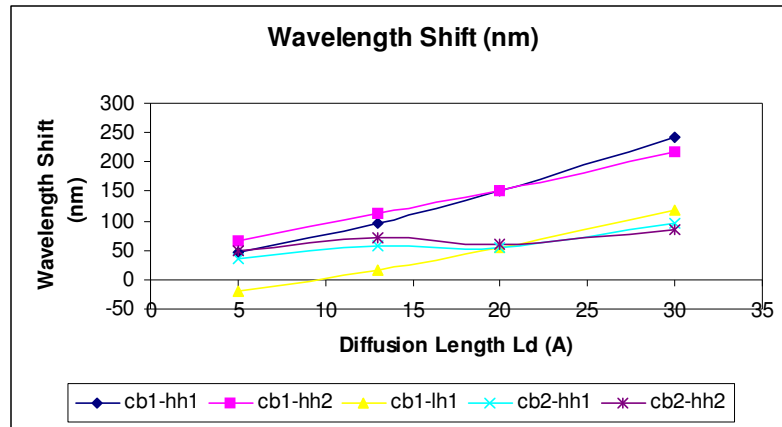
Simulations for different diffusion lengths (3)



Simulations for different diffusion lengths (4)



Simulations Summary



Ld (A)	Transition	λ Shift (meV)	λ Shift (nm)
5	cb1-hh1	23.8	47.0
13	cb1-hh1	49.4	94.7
20	cb1-hh1	82.8	152.5
30	cb1-hh1	140.4	242.5

Material composition difference between QW and barriers of our laser structure: Al: 0.221, Ga: 0.019, In: 0.23
 the shift for Ld = 30 A: 140.4 meV, Lz = 85A
 RTA@675C, 12 mins, shift ~9meV, corresponding to Ld<5 A

In simulations of GaAs/Al_{0.3}Ga_{0.7}As system, the material composition difference between QW and barriers: Al: 0.3, Ga: 0.3. the shift for Ld = 30 A: ~50 meV, Lz = 80A.

(90A GaAs/100A Al_{0.3}Ga_{0.7}As RTA@950C, 12 sec, shift 40 meV, corresponding to Ld~= 30 A.

* (O'Brien (1991), Interdiffusion of III-V Semiconductor Quantum Well Heterostructures and Its Applications to Integrated Electro-Optical Devices, PhD thesis, Cornell University)

Diffusion Coefficient D and Diffusion Length L_d

- **Activation Energy: E_A**
- **Coefficient D_0**
- **RTA Temperature: T**
- **RTA time: t**

$$D = D_0 \exp(-E_A / kT) \quad (5)$$

$$L_d = \sqrt{D \cdot t} \quad (6)$$



Future Work

- **2nd ion implantation**
 - Preprocess: photolithography and etching.
- **Simulations**
 - Investigate diffusion mechanism, refine the diffusion model.
 - Study how quantum well thickness and material composition differences play roles in quantum well intermixing.
 - Continue research on AlGaInAs material systems
 - Compare with InGaAsP material systems

